12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130730000
Alternate Assembly Site Qualification
Change Notification / Sample Request

Date: 8/2/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130730000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPD12S521DBTR	null
TXS02326AMRGER	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130730000	**PCN Date:**	08/02/2013
Title:	Alternate Assembly Site Qualification		
Customer Contact:	PCN Manager	**Phone:** +1(214)480-6037	**Dept:** Quality Services
Proposed 1st Ship Date:	11/02/2013	**Estimated Sample Availability:**	09/02/2013

Change Type:

☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

Qualification of TI Taiwan and TI Malaysia as an alternate Assembly sites for select devices as shown below. The material set will remain unchanged for both groups.

Reason for Change:

Continuous Customer Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Group 1

Assembly Site		
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA
TI Taiwan	Assembly Site Origin (22L)	ASO: TAI

Group 2

Assembly Site		
TI Clark (Philippines)	Assembly Site Origin (22L)	ASO: QAB
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA

Sample product shipping label (not actual product label)

Topside Device marking:
Assembly site code for TI Clark = I
Assembly site code for TI Malaysia = K
Assembly site code for TI Taiwan = T

Product Affected:			
Group 1: Adding TI Taiwan			
HPA00694DBTR	HPA00954DBTR	TPD12S521DBTR/2354	TPD12S521DBTRG4
HPA00885DBTR	TPD12S521DBTR		
Group 2: Adding TI Malaysia			
TXS02326AMRGER			

TI Taiwan Qualification Data: Approved July 2013

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: TPD12S521DBTR (MSL2-260C)

Package Construction Details

Assembly Site:	TAI	Mold Compound:	4206193
# Pins-Designator, Family:	38-DBT, TSSOP	Mount Compound:	4042500
Lead Finish:	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail
Electrical Characterization	Per PDS range	Pass
X-ray	(top side only)	Pass

TI Taiwan Reference Qualification Data: Approved January 2008

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: BQ8015DBT (MSL 2-260c)

Package Construction Details

Assembly Site:	TAI	Mold Compound:	4206193
# Pins-Designator, Family:	38-DBT, TSSOP	Mount Compound:	4042500
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot 3
**High Temp Operating Life	155C (240 Hrs)	40/0	40/0	40/0
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	40/0	40/0	40/0
**Autoclave 121C	121C, 2 ATM (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
**Thermal Shock	-65C/+150C (500 Cyc)	77/0	77/0	77/0

Notes: **Tests received preconditioning sequence: MSL2-260C

TI Malaysia Qualification Data: Approved July 2013

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: TXS02326AMRGER (MSL2-260C)

Package Construction Details

Assembly Site:	MLA	Mold Compound:	4208625
# Pins-Designator, Family:	24-RGE, VQFN	Mount Compound:	4205846
Lead Finish:	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail
Electrical Characterization	Per PDS range	Pass
X-ray	(top side only)	Pass

TI Malaysia Reference Qualification Data: Approved March 2007

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: TSC2200RHB (MSL 2-260c)

Package Construction Details

Assembly Site:	MLA	Mold Compound:	4208625
# Pins-Designator, Family:	24-RGE, VQFN	Mount Compound:	4205846
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot 3
**Steady-state Life Test	150C (168, 300 Hrs)	116/0	116/0	116/0
**High Temp. Storage Bake	150C (1000 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	40/0	40/0	40/0
**Autoclave 121C	121C, 2 ATM (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Notes: **Tests received preconditioning sequence: MSL2-260C				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com